RELIABILITY REPORT

FOR

MAX6025AEUR+

PLASTIC ENCAPSULATED DEVICES

August 6, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX6025AEUR+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX6012, MAX6021, MAX6025, MAX6030, MAX6041, MAX6045, MAX6050 precision, low-dropout, micropower voltage references are available in miniature SOT23-3 surface-mount packages. They feature a proprietary curvature-correction circuit and laser-trimmed thin-film resistors that result in a low temperature coefficient of <15ppm/°C and initial accuracy of better than 0.2%. These devices are specified over the extended temperature range. These series-mode voltage references draw only 27µA of quiescent supply current and can sink or source up to 500µA of load current. Unlike conventional shunt-mode (two-terminal) references that waste supply current and require an external resistor, devices in the MAX6012 family offer a supply current that's virtually independent of supply voltage (with only a 0.8µA/V variation with supply voltage) and do not require an external resistor. Additionally, these internally compensated devices do not require an external compensation capacitor and are stable with up to 2.2nF of load capacitance. Eliminating the external compensation capacitor saves valuable board area in space-critical applications. Their low dropout voltage and supply-independent, ultra-low supply current make these devices ideal for battery-operated, low-voltage systems.

II. Manufacturing Information

A. Description/Function:	Precision, Low-Power, Low-Dropout, SOT23-3 Voltage References
B. Process:	B12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon, California or Texas
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	July 25, 1998

III. Packaging Information

A. Package Type:	3-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	84-1lmisr4
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0901-0154
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	250*°C/W
K. Single Layer Theta Jc:	130°C/W
L. Multi Layer Theta Ja:	n/a
M. Multi Layer Theta Jc:	n/a

IV. Die Information

A. Dimensions:	44 X 31 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{1000 \times 4340 \times 228 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 0.9 \times 10^{-9}$

λ = 0.9 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the B12 Process results in a FIT Rate of 0.06 @ 25C and 1.06 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The RF23-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX6025AEUR+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	228	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data